

OCT 04 2005

Docket No. **FILL IN DOCKET NO.** 743421-82**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of:

Masuo KONDO et al.

Application No. 10/529,172

Filed: March 24, 2005

For: SOLDER BALL, METHOD OF MAKING
THE SAME, AND METHOD OF MAKING
SEMICONDUCTOR INTERCONNECT
STRUCTURE

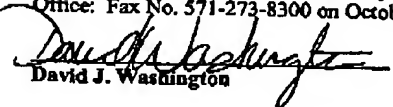
) ATTENTION:

) OFFICE OF INITIAL PATENT

) EXAMINATION'S FILING

) RECEIPT CORRECTIONS

) Group Art Unit: 2812

CERTIFICATE OF TRANSMISSIONI hereby certify that this correspondence is being facsimile transmitted to the United States Patent and Trademark
Office: Fax No. 571-273-8300 on October 3, 2005
David J. Washington**REQUEST FOR CORRECTED OFFICIAL FILING RECEIPT**Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Enclosed is a copy of the Official Filing Receipt marked to show a correction that is needed. The correction is as follows: The Title should read – SOLDER BALL, METHOD OF MAKING THE SAME, AND METHOD OF MAKING SEMICONDUCTOR INTERCONNECT STRUCTURE--. The first Foreign Priority should read –JAPAN 2002-283301 09/27/02--.

Attached hereto is a copy of the Application Data Sheet.

Issuance of a corrected Official Filing Receipt is respectfully requested.

Respectfully submitted,

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